# **4-Line Transient Voltage Suppressor Array**

This 4-line voltage transient suppressor array is designed for application requiring transient voltage protection capability. It is intended for use in over-transient voltage and ESD sensitive equipment such as cell phones, portables, computers, printers and other applications. This device features a common cathode design which protects four independent lines in a single SOT-563 package.

### Features

- Protects up to 4 Lines in a Single SOT-563 Package
- ESD Rating: IEC61000–4–2: Level 4
  - Contact (8 kV), Air (15 kV)
- V<sub>CC</sub> Pin = 16 V Protection D1, D2, and D3 Pins = 6.8 V Protection
- Low Capacitance (< 7 pF @ 3 V) for D<sub>1</sub>, D<sub>2</sub>, and D<sub>3</sub>
- This is a Pb–Free Device

### Applications

- Hand Held Portable Applications
- USB Interface
- Notebooks, Desktops, Servers
- SIM Card Protection

### **MAXIMUM RATINGS** ( $T_J = 25^{\circ}C$ , unless otherwise specified)

Symbol	Rating	Value	Unit
P <sub>PK</sub> 1	Peak Power Dissipation V <sub>CC</sub> Diode 8x20 μsec double exponential waveform,	200	W
	(Note 1) D <sub>1</sub> , D <sub>2</sub> , and D <sub>3</sub>	20	W
TJ	Operating Junction Temperature Range	-40 to 125	°C
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
ΤL	Lead Solder Temperature – Maximum (10 seconds)	260	°C
ESD	IEC 61000–4–2 Air IEC 61000–4–2 Contact	15000 8000	V

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Nonrepetitive current pulse per Figure 1.

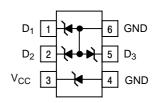


## **ON Semiconductor®**

http://onsemi.com

# SOT-563 4-LINE TRANSIENT VOLTAGE SUPPRESSOR

### **PIN ASSIGNMENT**



### MARKING DIAGRAM





MT = Specific Device Code

M = Date Code

SOT-563

CASE 463A STYLE 6

- = Pb-Free Package
- (Note: Microdot may be in either location)

### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NUP4060AXV6T1G	SOT–563 (Pb–Free)	

<sup>+</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

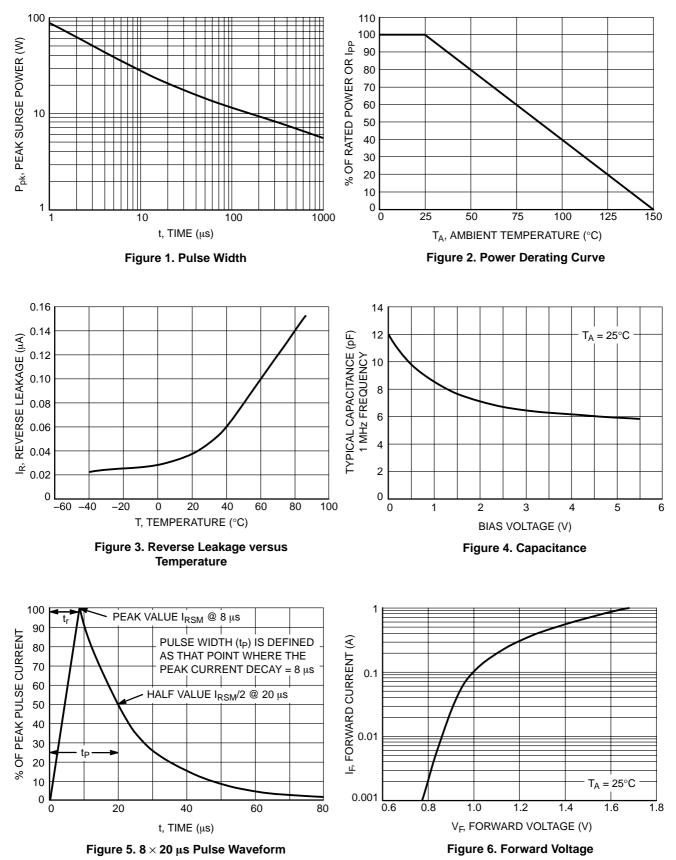
# **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = $25^{\circ}$ C, unless otherwise specified)

Parameter	Conditions	Symbol	Min	Тур	Max	Unit
Reverse Working Voltage $(D_1, D_2, and D_3)$	(Note 2)	V <sub>RWM</sub>	-	-	5.0	V
Breakdown Voltage ( $D_1$ , $D_2$ , and $D_3$ )	I <sub>T</sub> = 1 mA, (Note 3)	V <sub>BR</sub>	6.2	6.8	7.2	V
Breakdown Voltage (V <sub>CC</sub> )	I <sub>T</sub> = 5 mA, (Note 3)	V <sub>BR2</sub>	15.3	16	17.1	V
Reverse Leakage Current ( $D_1$ , $D_2$ , and $D_3$ )	V <sub>RWM</sub> = 3 V	I <sub>R</sub>	-	0.01	0.5	μΑ
Reverse Leakage Current (V <sub>CC</sub> )	V <sub>BR</sub> = 11 V	Ι <sub>R</sub>	-	-	0.05	μΑ
Capacitance $(D_1, D_2, and D_3)$	$V_R$ = 3 V, f = 1 MHz (Line to GND)	CJ	-	7	10	pF

TVS devices are normally selected according to the working peak reverse voltage (V<sub>RWM</sub>), which should be equal or greater than the DC or continuous peak operating voltage level.
 V<sub>BR</sub> is measured at pulse test current I<sub>T</sub>.



(Diode D<sub>1</sub>, D<sub>2</sub>, and D<sub>3</sub> only)



#### PACKAGE DIMENSIONS

### SOT-563, 6 LEAD

CASE 463A-01 ISSUE F

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NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.



 MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

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 C
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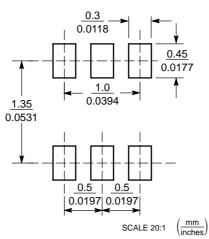
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 E
 1.10
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 HE
 1.50
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#### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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